Filename: PMP10182RevB - BoM.xls

Variant: None

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PMP10182 REV B Bill of Materials

Item #	Designator	Quantity	Value	PartNumber	Manufacturer	Description	PackageReference
1	C2	1	1uF	C3216X7R2A105M160AA	TDK	CAP, CERM, 1 µF, 100 V, +/- 20%, X7R, 1206	1206
2	C4	1	0.1uF	06035C104KAT2A	AVX	CAP, CERM, 0.1 μF, 50 V, +/- 10%, X7R, 0603	0603
3	C5	1	1800pF	06031C182JAT2A	AVX	CAP, CERM, 1800 pF, 100 V, +/- 5%, X7R, 0603	0603
4	C6	1	4.7pF	06035A4R7CAT2A	AVX	CAP, CERM, 4.7 pF, 50 V, +/- 5%, C0G/NP0, 0603	0603
5	C7	1	4.7uF	C3216X7R1E475K	TDK	CAP, CERM, 4.7 μF, 25 V, +/- 10%, X7R, 1206	1206
6	J1, J2	2		ED555/2DS	On-Shore Technology	Terminal Block, 6A, 3.5mm Pitch, 2-Pos, TH	7.0x8.2x6.5mm
7	L1	1	47uH	LPS3015-473MLB	Coilcraft	Inductor, Shielded Drum Core, Ferrite, 47 µH, 0.39 A, 1.55 ohm, SMD	LPS3015
8	R3	1	54.9k	CRCW060354K9FKEA	Vishay-Dale	RES, 54.9 k, 1%, 0.1 W, 0603	0603
9	R4, R6	2	100k	CRCW0603100KFKEA	Vishay-Dale	RES, 100 k, 1%, 0.1 W, 0603	0603
10	R5	1	49.9	CRCW060349R9FKEA	Vishay-Dale	RES, 49.9, 1%, 0.1 W, 0603	0603
11	R7	1	9.76k	CRCW06039K76FKEA	Vishay-Dale	RES, 9.76 k, 1%, 0.1 W, 0603	0603
12	TP1, TP5	2	Red	5000	Keystone	Test Point, Miniature, Red, TH	Red Miniature Testpoint
13	TP2, TP6, TP7	3	Black	5001	Keystone	Test Point, Miniature, Black, TH	Black Miniature Testpoint
14	TP3, TP4	2	White	5002	Keystone	Test Point, Miniature, White, TH	White Miniature Testpoint
15	U1	1		TPS54061DRBR		Buck Step Down Regulator with 4.7 to 60 V Input and 0.8 to 58 V Output, -40 to 125 degC, 8-Pin SON (DRB), Green (RoHS & no Sb/Br)	DRB0008B

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